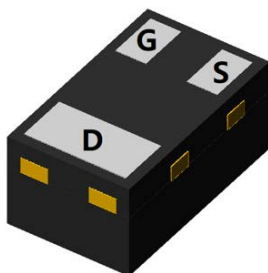


N-Channel Enhancement Mode Field Effect Transistor

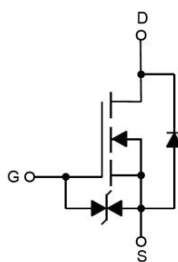


Top View



Bottom View

DFN1006-3L



Product Summary

- V_{DS} 30V
- I_D 1.4A
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $<240m\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=2.5V$) $<300m\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=1.8V$) $<500m\Omega$
- ESD Protected Up to 3.0KV (HBM)

General Description

- Trench Power MV MOSFET technology
- Voltage controlled small signal switch
- Low input Capacitance
- Fast Switching Speed
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Battery operated systems
- Solid-state relays
- Direct logic-level interface: TTL/CMOS

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	30	V
Gate-source Voltage		V_{GS}	± 10	V
Drain Current	$T_A=25^\circ C$	I_D	1.4	A
	$T_A=100^\circ C$		0.9	
Pulsed Drain Current ^A		I_{DM}	5	A
Total Power Dissipation ^B	$T_A=25^\circ C$	P_D	0.8	W
	$T_A=100^\circ C$		0.3	
Junction and Storage Temperature Range		T_J, T_{STG}	$-55 \sim +150$	$^\circ C$

■ Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^C	Steady-State	$R_{\theta JA}$	125	150	$^\circ C/W$

■ Ordering Information (Example)

PREFERED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCA01N03KA	F1	13	10000	100000	400000	7" reel

■ Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	μA
		V _{DS} =30V, V _{GS} =0V, T _J =150°C	-	-	100	
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±10V, V _{DS} =0V	-	-	±10	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	0.45	0.75	1	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =1.4A	-	180	240	mΩ
		V _{GS} =2.5V, I _D =1.2A	-	225	300	
		V _{GS} =1.8V, I _D =1.0A	-	330	500	
Diode Forward Voltage	V _{SD}	I _S =1.4A, V _{GS} =0V	-	0.9	1.2	V
Maximum Body-Diode Continuous Current	I _S		-	-	1.4	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1MHz	-	60	-	pF
Output Capacitance	C _{oss}		-	11	-	
Reverse Transfer Capacitance	C _{rss}		-	4	-	
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =1.4A	-	2.4	-	nC
Gate-Source Charge	Q _{gs}		-	0.6	-	
Gate-Drain Charge	Q _{gd}		-	0.4	-	
Reverse Recovery Charge	Q _{rr}	I _F =1.4A, di/dt=50A/us	-	0.6	-	nC
Reverse Recovery Time	t _{rr}		-	8.6	-	ns
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =15V, I _D =1.4A R _{GEN} =3Ω	-	3	-	ns
Turn-on Rise Time	t _r		-	22	-	
Turn-off Delay Time	t _{D(off)}		-	4	-	
Turn-off fall Time	t _f		-	21	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. P_d is based on max. junction temperature, using junction-case thermal resistance.

C. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in the still air environment with $T_A=25^{\circ}\text{C}$. The maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

■ Typical Electrical and Thermal Characteristics Diagrams

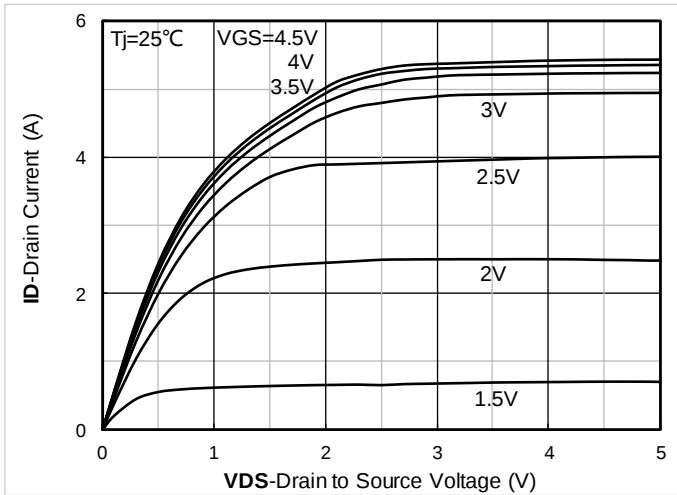


Figure 1. Output Characteristics

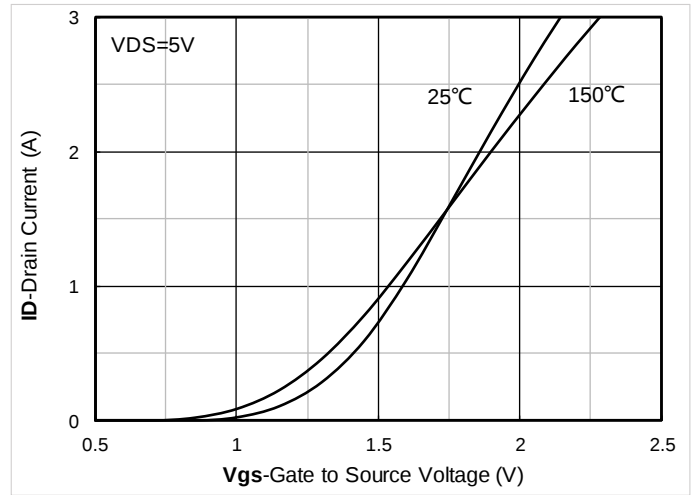


Figure 2. Transfer Characteristics

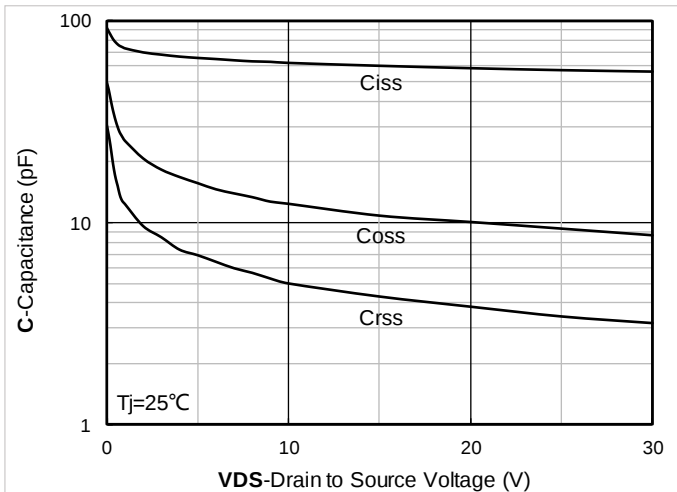


Figure 3. Capacitance Characteristics

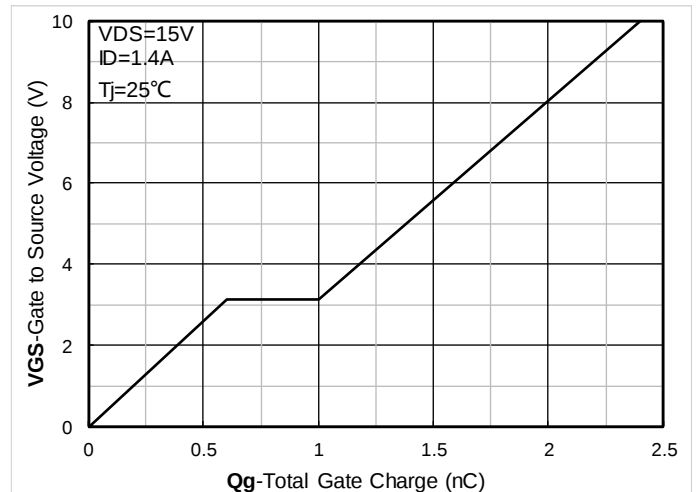


Figure 4. Gate Charge

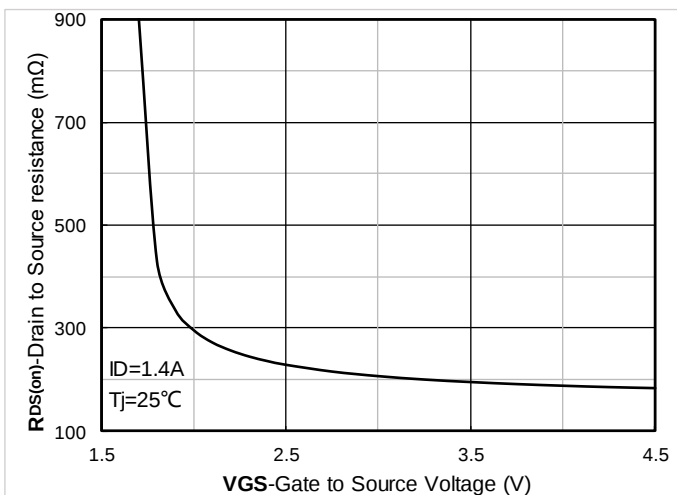


Figure 5. On-Resistance vs Gate to Source Voltage

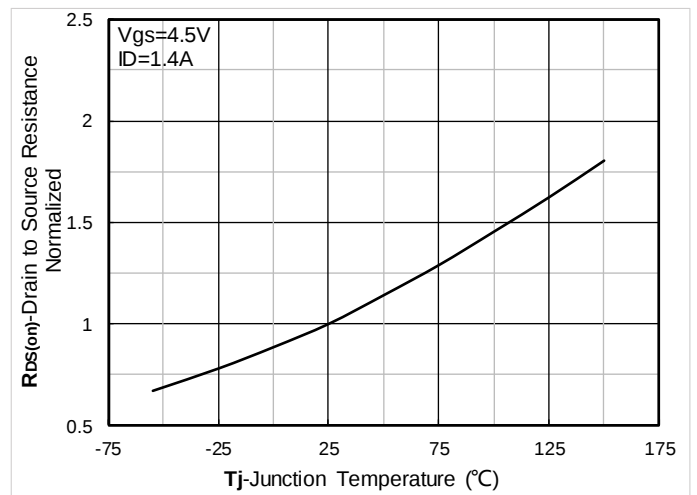


Figure 6. Normalized On-Resistance

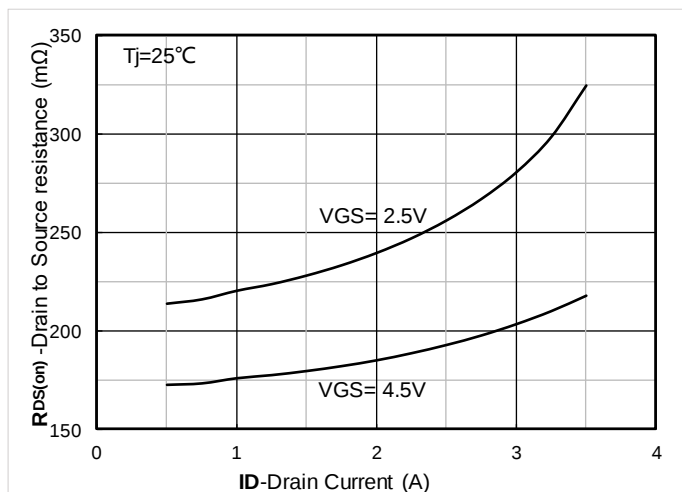


Figure 7. $R_{DS(on)}$ VS Drain Current

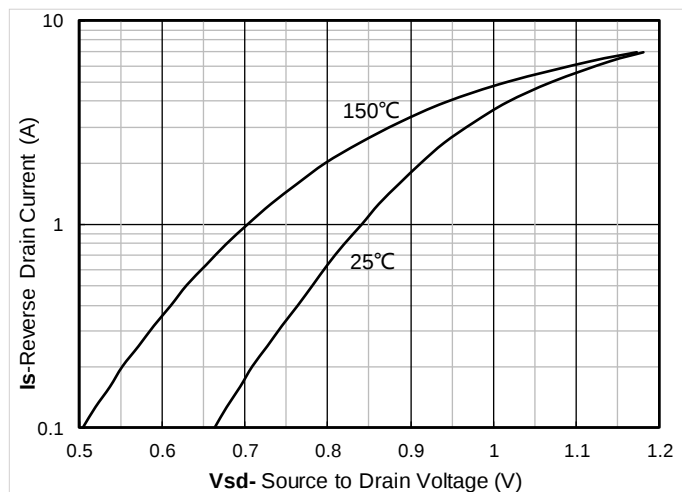


Figure 8. Forward characteristics of reverse diode

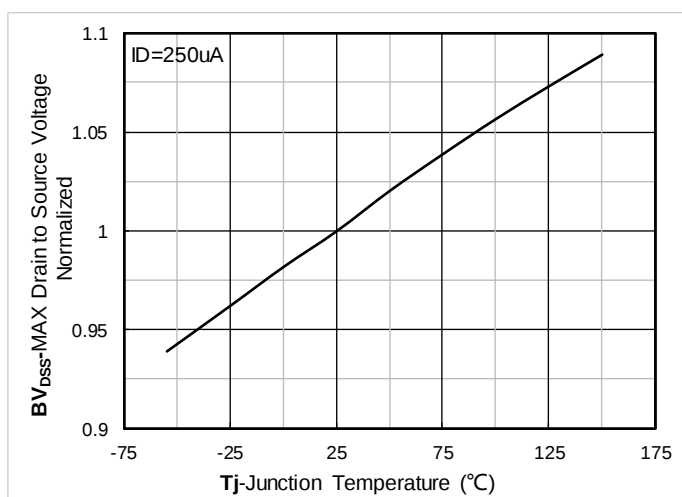


Figure 9. Normalized breakdown voltage

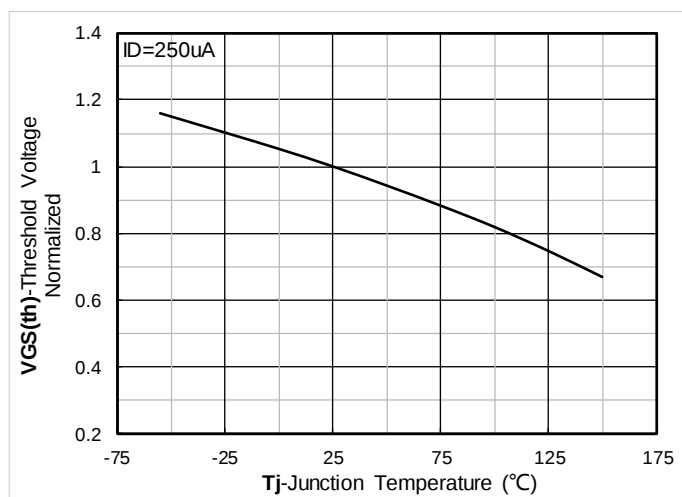


Figure 10. Normalized Threshold voltage

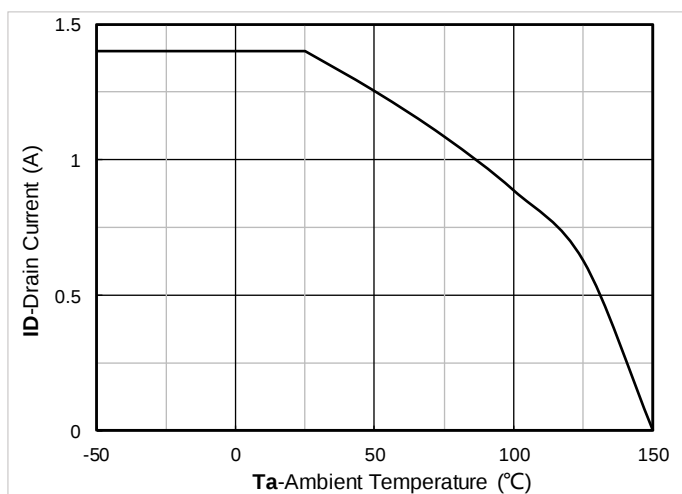


Figure 11. Current dissipation

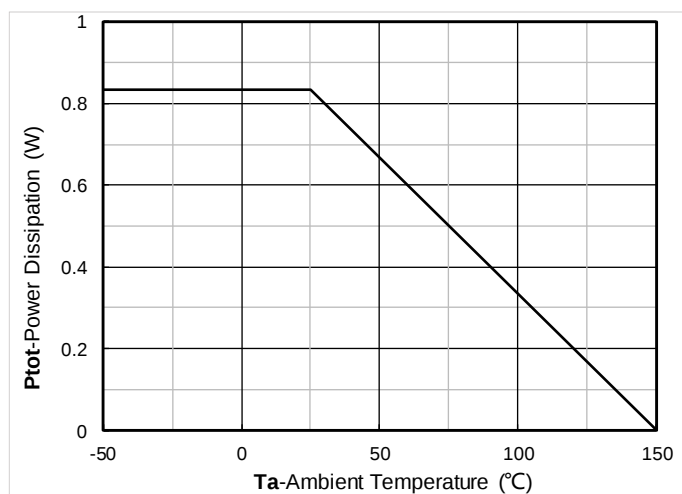


Figure 12. Power dissipation

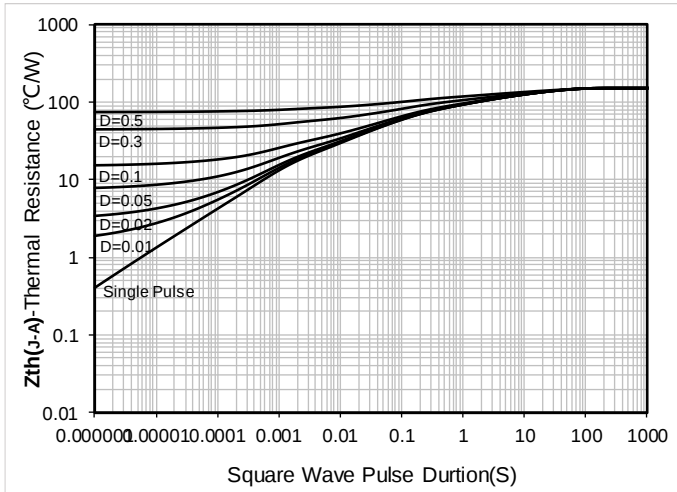


Figure 13. Maximum Transient Thermal Impedance

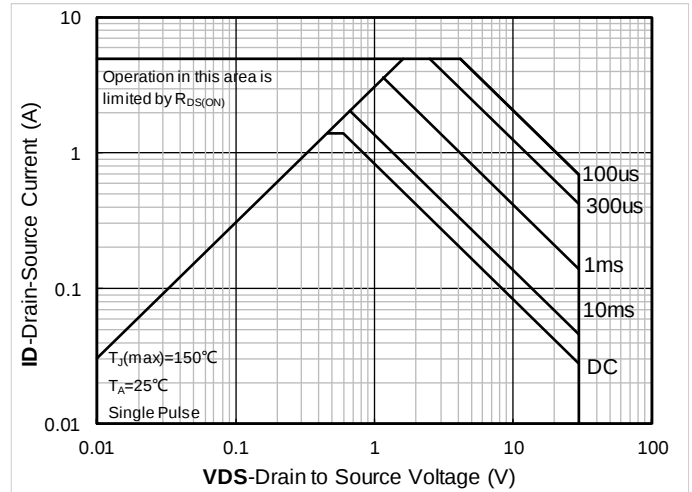


Figure 14. Safe Operation Area

Test Circuits & Waveforms

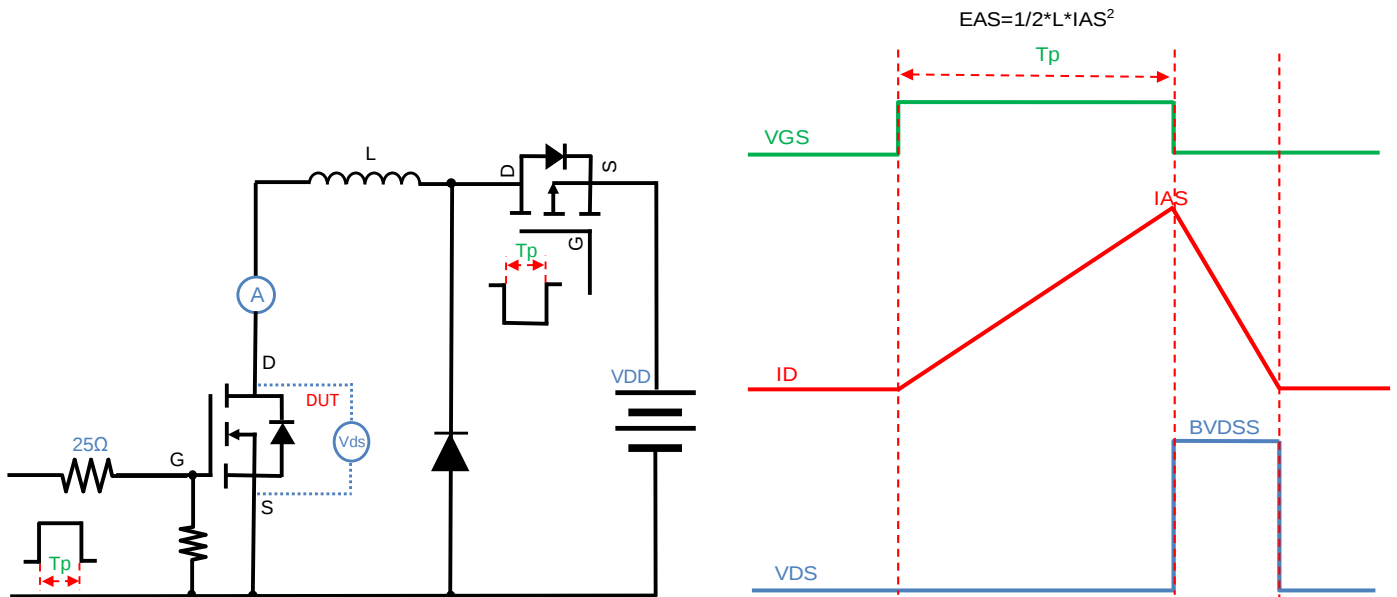


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

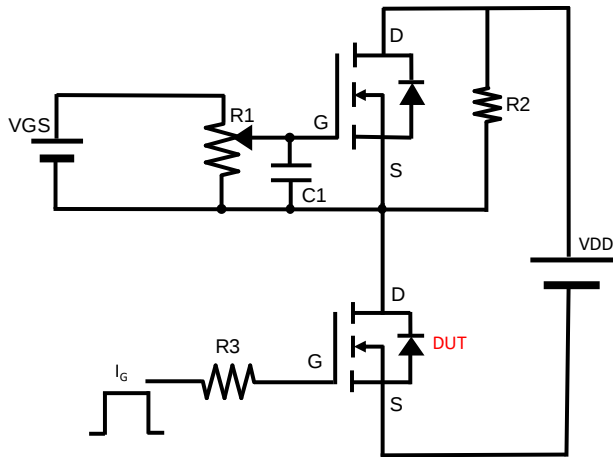


Figure B. Gate Charge Test Circuit & Waveform

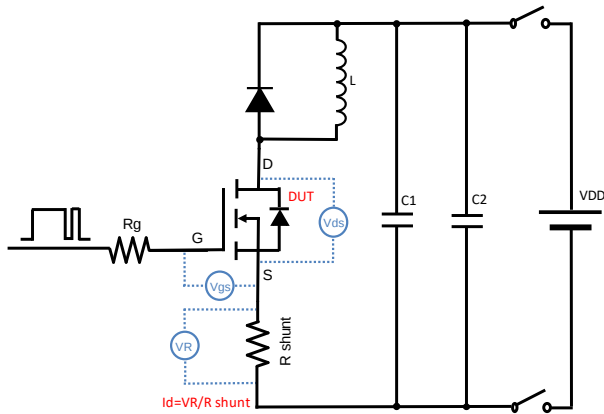


Figure C. Resistive Switching Test Circuit & Waveform

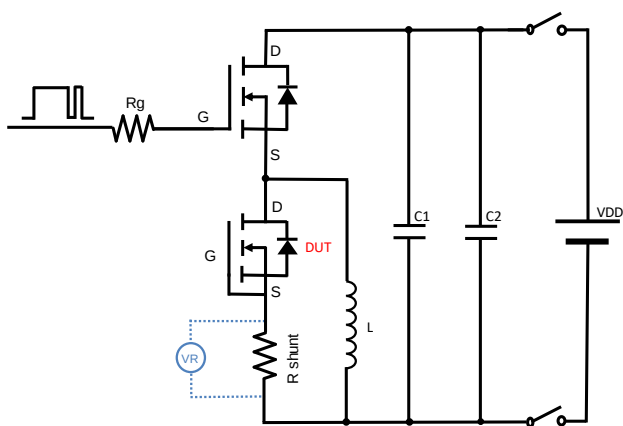
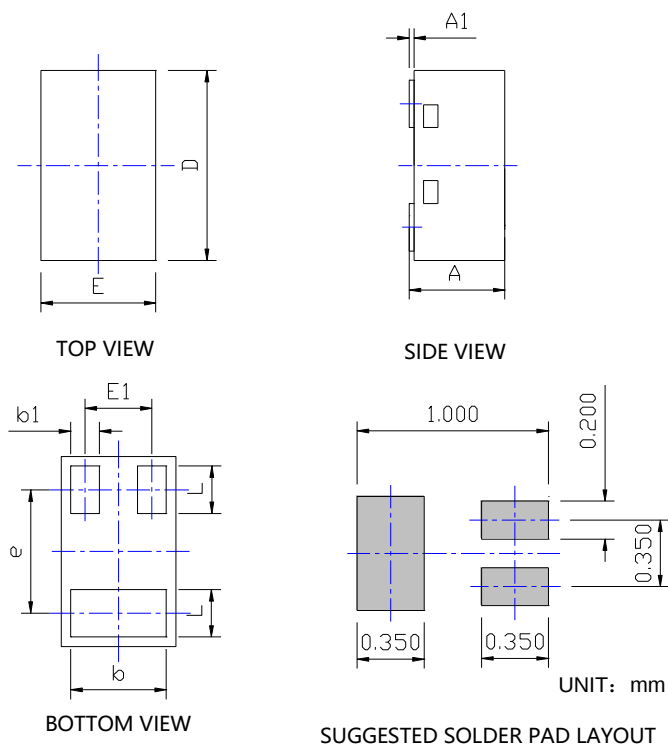


Figure D. Diode Recovery Test Circuit & Waveform

■ DFN1006-3L Package information



SYMBOL	DIMENSIONS		
	Millimeter		
	MIN.	NOM.	MAX.
A	0.42	---	0.55
A1	0.025REF		
b	0.45	0.50	0.55
b1	0.10	0.15	0.20
D	0.95	1.00	1.05
E	0.55	0.60	0.65
E1	0.35BSC		
e	0.65BSC		
L	0.20	0.25	0.30

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE LEAD BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

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